



Product Change Notification / LIAL-14KZIS105

Date:

04-Jul-2023

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6194 and 6194.001 Final Notice: Qualification of MTAI as an additional assembly site for selected ATtiny13, ATtiny25 and QT113B device families available in 8L SOIC 3.90mm(.150in) package with MSL 1 classification.

Affected CPNs:

[LIAL-14KZIS105_Affected_CPN_07042023.pdf](#)

[LIAL-14KZIS105_Affected_CPN_07042023.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of MTAI as an additional assembly site for selected ATtiny13, ATtiny25 and QT113B device families available in 8L SOIC 3.90mm(.150in) package with MSL 1 classification

Pre and Post Change Summary:

	Pre change		Post Change		
Assembly Site	Lingsen Precision Industries, LTD. (LPI)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Lingsen Precision Industries, LTD. (LPI)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (HQ) (MTAI)
Wire Material	CuPdAu/Au	Cu / Au	CuPdAu/Au	Cu / Au	Au
Die Attach Material	CRM-1033BF	8290	CRM-1033BF	8290	8390A
Molding Compound Material	G600	G600/G700LS	G600	G600/G700LS	G600V
Lead-Frame Material	C194	C194	C194	C194	CDA194
Lead-Frame Paddle Size	95 x 130 mils	90 x 130 mils/95x155 mils	95 x 130 mils	90 x 130 mils/95x155 mils	90x90mils/ 95x130 mils
DAP Surface Prep	Ag ring plate	Ag ring plate	Ag ring plate	Ag ring plate	Bare Cu
Lead-lock	No	No	No	No	Yes
Lead-Frame Design	See attached pre and post change comparison				
Moisture Sensitivity Level (MSL)	MSL 2	MSL 2	MSL 2	MSL 2	MSL 1

Note: * C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference”

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:August 26, 2023 (date code: 2334)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2023					August 2023				
Workweek	26	27	28	29	30	31	32	33	34	35

Qual Report Availability		x								
Final PCN Issue Date		x								
Estimated Implementation Date									x	

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:July 4, 2023: Issued final notification

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-14KZIS105 Qual Report.pdf](#)

[PCN_LIAL-14KZIS105 Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATTINY13-20SSU
ATTINY13V-10SSU
ATTINY13-20SSQ
ATTINY13-20SSQR
ATTINY13-20SSUR
ATTINY13V-10SSUR
ATTINY25-20SSU
ATTINY25V-10SSU
ATTINY25V-10SSN
ATTINY25-20SSN
ATTINY25V-10SSNR
ATTINY25-20SSNR
ATTINY25-20SSUR
ATTINY25V-10SSUR
QT113B-ISG